Thermoelectric Module



Scope

This specification is applied to multicomp thermoelectric modules Revision of these specifications is carried out after consent

Specifications

Para	Remarks			
Internal resistance	1.25 Ω	Note-1		
l max.	6	Note-2		
V max.	8.8	Note-3		
-	Th = 27°C	Th = 50°C	-	
Q max.	31.1 W	34.2 W	Note-4	
ΔT max.	70°C	77°C	Note-5	
Solder melting point	235	Note-6		
Maximum compress	1 M	Note-7		

Note-1 : Measured by AC 4 - terminal method at 25°C

Note-2 : Maximum current at ΔT max.

Note-3 : Maximum voltage at ΔT max.

Note-4 : Maximum cooling capacity at I max. V max. and $\Delta T = 0^{\circ}C$

Note-5 : Maximum temperature difference at I max. V max. and Q = 0 W

(Maximum parameters are measured in a vacuum 1.3 P)

Note-6 : The solder melting point of thermoelectric module

Note-7 : Recommended maximum compression (not destruction limit)

Specificat	ion Table	Thot = 27°C					
I max. (A)	U max. (V)	Qc max. W	dT max. °C	Α	В	н	Part Number
6	8.8	31.1	70	30	30	3.95	MCPE1-07107AC-S
Dimensional Millimation							

Dimensions : Millimetres

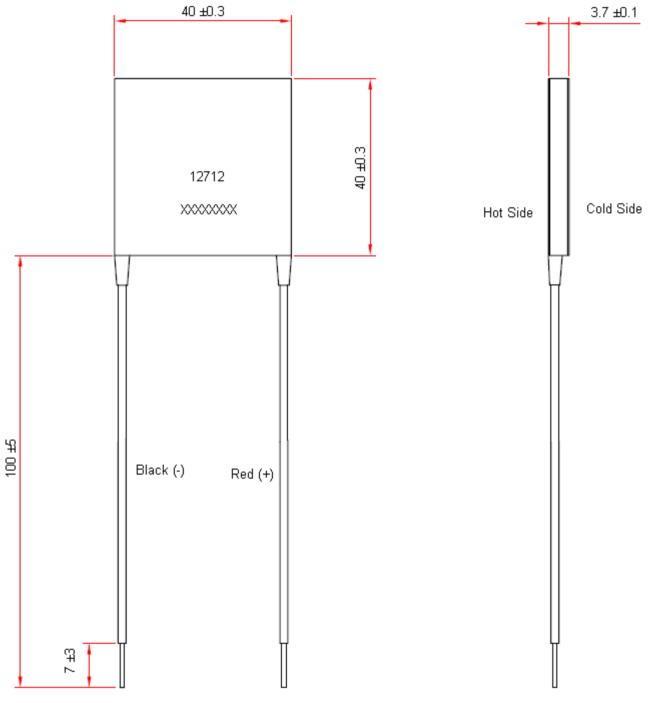
PE1 Modules have specification of -40 to +100°C operation, and are silicone sealed for moisture protection



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Outline Drawing



Dimensions : Millimetres

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